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- (71) Applicant (for all designated States except US): **UNIVERSITY OF MANCHESTER INSTITUTE OF SCIENCE AND TECHNOLOGY** [GB/GB]; P.O. Box 88, Manchester M60 1QD (GB).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **WOOD, Alan, Keith** [GB/GB]; Laurel House, Milburn, Penrith, Cumbria CA10 1TW (GB). **DAY, Richard, John** [GB/GB]; 5 The Quadrant, Romiley, Stockport, Cheshire SK6 3AY (GB). **WILLIAMS, Martin, Allen** [GB/GB]; 16 Westland Chase, West Winch, King Lynn, Norfolk PE33 0QH (GB). **HALL, David** [GB/GB]; Manchester Material Science Centre, Grosvenor Street, Manchester M1 7HS (GB). **STOCKIL, Cyril** [IE/IE]; 8 Lynn Road, Mullingar, County Westmeath (IE).
- (74) Agent: **ATKINSON, Peter, Birch**; Marks & Clerk, Sussex House, 83-85 Mosley Street, Manchester M2 3LG (GB).
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(54) Title: CURABLE DIELECTRIC POLYNORBORNENE COMPOSITION AND CIRCUIT BOARDS MADE THEREFROM

(57) Abstract: The present invention relates to a curable dielectric composition comprising polynorbornene, a polymeric diluent that plasticises the composition, a particulate material and a curing agent for the composition. The present invention also relates to a cured form of the curable composition and an electronic circuit board including a cured form of the composition upon which is mounted an electronic circuit.



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